

Smart High-Side Power Switch



Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown
- Overvoltage protection
- Fast demagnetization of inductive loads
- Reverse battery protection¹)
- Open drain diagnostic output
- Open load detection in OFF-state
- CMOS compatible input
- Loss of ground and loss of V_{bb} protection
- Electrostatic discharge (ESD) protection
- Green Product (RoHS compliant)
- AEC Qualified

Product Summary

Overvoltage protection	V _{bb(AZ)}	65	V
Operating voltage	$V_{ m bb(on)}$	5.8 5	8 V
On-state resistance	Ron	250	$m\Omega$
Load current (ISO)	/L(ISO)	1.7	Α

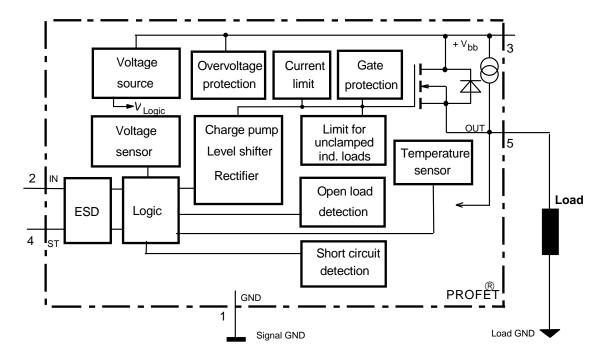


Application

- μC compatible power switch with diagnostic feedback for 12 V and 24 V DC grounded loads
- Most suitable for inductive loads
- Replaces electromechanical relays, fuses and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS[®] technology. Providing embedded protective functions.



¹⁾ With external current limit (e.g. resistor R_{GND}=150 Ω) in GND connection, resistor in series with ST connection, reverse load current limited by connected load.



Pin	Symbol		Function
1	GND		Logic ground
2	IN	-	Input, activates the power switch in case of logical high signal
3	Vbb	+	Positive power supply voltage, the tab is shorted to this pin
4	ST	S	Diagnostic feedback
5	OUT (Load, L)	0	Output to the load

Maximum Ratings at $T_j = 25$ °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 3)	$V_{\rm bb}$	65	V
Supply voltage for short circuit protection ² T _{j Start} =-40+150°C	$V_{ m bb}$	40	V
Load current (Short circuit current, see page 4)	<i>I</i> L	self-limited	Α
Operating temperature range	T _j	-40+150	°C
Storage temperature range	T_{stg}	-55 + 150	
Power dissipation (DC), T _C ≤ 25 °C	P _{tot}	50	W
Electrostatic discharge capability (ESD) IN, ST: (Human Body Model) all other pins:	V _{ESD}	1.0 tbd (>1.0)	kV
Input voltage (DC)	V _{IN}	-0.5 +36	V
Current through input pin (DC)	I _{IN}	±2.0	mA
Current through status pin (DC)	I _{ST}	±5.0	
see internal circuit diagrams page 5			

Thermal Characteristics

Parameter and Conditions		Symbol		Values	}	Unit
			min	typ	max	_
Thermal resistance	chip - case:	R_{thJC}			2.5	K/W
	junction - ambient (free air):	R_{thJA}			75	

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Status fault signal in case of short to GND. Internal thermal shutdown after several milliseconds. External shutdown in response to the status fault signal in less than about 1 ms necessary, if the device is used with higher V_{bb}.



Electrical Characteristics

Parameter and Conditions	Symbol		Values	;	Unit
at $T_j = 25$ °C, $V_{bb} = 12$ V unless otherwise specified		min	typ	max	

Load Switching Capabilities and Characteristics

On-state resistance (pin 3 to 5)						
$I_{L} = 2 \text{ A}, \ V_{bb} = 24 \text{ V}$	<i>T</i> j=25 °C:	R_{ON}		220	250	$m\Omega$
	<i>T</i> j=150 °C:			390	500	
Nominal load current, ISO Norm (pin 3	3 to 5)	_	1.4	1.7		_
$V_{\rm ON} = 0.5 \text{ V}, \ T_{\rm C} = 85 \text{ °C}$		$I_{L(ISO)}$				Α
Output current (pin 5) while GND disco	onnected or	I _{L(GNDhigh)}		-	1.1	mA
GND pulled up, $V_{bb}=32 \text{ V}$, $V_{IN}=0$, see	ee diagram					
page 6						
Turn-on time to 90% V_{OUT} :		<i>t</i> on	15		80	μS
Turn-off time to 10% V_{OUT} :		$t_{ m off}$	20		70	
$R_{\rm L} = 12 \ \Omega, \ V_{\rm bb} = 20 \text{V}, \ T_{\rm j} = -40+150$	°C					
Slew rate on, 10 to 30% V_{OUT} ,		dV/dt_{on}			6	V/μs
$R_L = 12 \Omega$, $V_{bb} = 20V$, $T_j = -40+150$ °C	C					
Slew rate off, 10 to 30% V_{OUT} ,		-d V/dt _{off}			7	V/μs
$R_L = 12 \Omega$, $V_{bb} = 20V$, $T_j = -40+150$ °C	0					
·			·		·	

Operating Parameters

. •						
Operating voltage 3)	<i>T</i> _j =-40+150°C:	V _{bb(on)}	5.8		58	V
Undervoltage shutdown	<i>T</i> _j =-40+150°C:	V _{bb(under)}	2.7		4.7	V
Undervoltage restart	<i>T</i> _j =-40+150°C:	V _{bb(u rst)}			4.9	V
Undervoltage restart of charge see diagram page 10	pump T _j =-40+150°C:	$V_{ m bb(ucp)}$		5.6	7.5	V
Undervoltage hysteresis $\Delta V_{bb(under)} = V_{bb(u rst)} - V_{bb(under)}$		$\Delta V_{ m bb(under)}$	1	0.4		V
Overvoltage protection ⁴⁾	$T_{\rm j}$ =-40+150°C:	$V_{\rm bb(AZ)}$	65	70		V
<i>l</i> _{bb} =40 mA						
Standby current (pin 3),		I _{bb(off)}				μΑ
$V_{IN}=0$	<i>T</i> _j =-40+150°C:			10	50	
Operating current (Pin 1) ⁵⁾ , V _{IN} =	=5 V	I _{GND}		2.2		mA
		•		<u> </u>		

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³⁾ At supply voltage increase up to V_{bb} = 5.6 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V

See also $V_{ON(CL)}$ in table of protection functions and circuit diagram page 6.

⁵⁾ Add I_{ST} , if $I_{ST} > 0$, add I_{IN} , if $V_{IN} > 5.5 \text{ V}$



Parameter and Conditions	Symbol		Values		Unit
at $T_i = 25$ °C, $V_{bb} = 12$ V unless otherwise specified	- Cyllison	min	typ	max	Oiiit
Protection Functions ⁶)	<u> </u>	111111	ιyρ	max	
Initial peak short circuit current limit (pin 3 to 5)	I _{L(SCp)}				
Τ _j =-40°C: Τ _j =25°C: Τ _j =+150°C:		 4.0	 10 	19 	A
Output clamp (inductive load switch off) at $V_{\text{OUT}} = V_{\text{bb}} - V_{\text{ON(CL)}}$ $I_{\text{L}} = 1 \text{ A}$, $T_{\text{j}} = -40+150^{\circ}\text{C}$:	V _{ON(CL)}	59		75	V
Thermal overload trip temperature	T_{jt}	150			°C
Thermal hysteresis	$\Delta T_{\rm jt}$		10		K
Reverse battery (pin 3 to 1) 7)	- V _{bb}			32	V
Diagnostic Characteristics Open load detection current (included in standby current Ibb(off))	I _{L(off)}		6		μА
Open load detection voltage T_i =-40150°C:	$V_{\text{OUT(OL)}}$	2.4	3	4	V
Short circuit detection voltage (pin 3 to 5)	V _{ON(SC)}		2.5		V
Input and Status Feedback ⁸⁾					
Input resistance see circuit page 5	Rı		20		kΩ
Input turn-on threshold voltage	$V_{\rm IN(T+)}$	1		2.5	V
Input turn-off threshold voltage	$V_{\rm IN(T-)}$	0.8			V
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$		0.5		V
Off state input current (pin 2), $V_{IN} = 0.4 \text{ V}$	/ _{IN(off)}	1		30	μА
On state input current (pin 2), $V_{IN} = 3.5$? V	I _{IN(on)}	10	25	70	μΑ
Delay time for status with open load after Input neg. slope (see diagram page 10)	t _{d(ST OL3)}		200		μS
Status output (open drain)					
Zener limit voltage $T_j = -40 + 150$ °C, $I_{ST} = +1.6$ mA:	V _{ST(high)}	5.4	6.1		V
ST low voltage $T_j = -40 + 150$ °C, $I_{ST} = +1.6$ mA:	$V_{\rm ST(low)}$			0.4	

Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

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Requires 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Note that the power dissipation is higher compared to normal operating conditions due to the voltage drop across the intrinsic drain-source diode. The temperature protection is not active during reverse current operation! Input and Status currents have to be limited (see max. ratings page 2 and circuit page 6).

⁸⁾ If a ground resistor R_{GND} is used, add the voltage drop across this resistor.



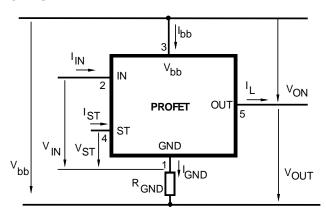
Truth Table

	Input-	Input- Output Sta		
	level	level	BTS307	
Normal	L	L	L	
operation	Н	Н	Н	
Open load	L	9)	Н	
_	Н	Н	Н	
Short circuit	L	L	L	
to GND	Н	L	L	
Short circuit	L	Н	Н	
to V _{bb}	Н	Н	Н	
Overtem-	L	L	L	
perature	Н	L	L	
Under-	L	L	L	
voltage	Н	L	L	
Overvoltage	no overvoltage shutdown,			
	see normal operation			

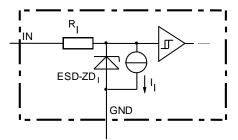
L = "Low" Level H = "High" Level X = don't care

care Z = high impedance, potential depends on external circuit Status signal after the time delay shown in the diagrams (see fig 5. page 10)

Terms

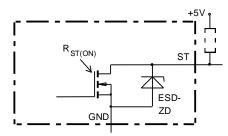


Input circuit (ESD protection)



ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

Status output

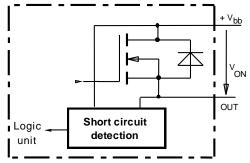


ESD-Zener diode: 6.1 V typ., max 5 mA;

 $R_{ST(ON)}$ < 0 Ω at 1.6 mA, ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

Short circuit detection

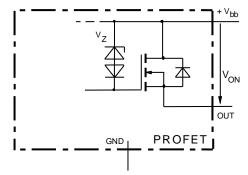
Fault Signal at ST-Pin: $V_{\rm ON} > 2.5$ V typ, no switch off by the PROFET itself, external switch off recommended!



⁹⁾ Power Transistor off, high impedance, internal pull up current source for open load detection.

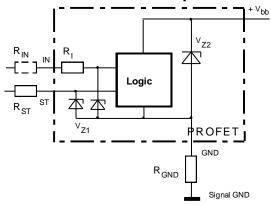


Inductive and overvoltage output clamp



Von clamped to -- V typ.

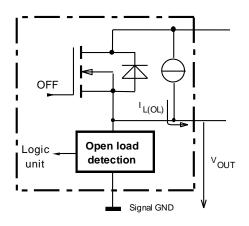
Overvolt. and reverse batt. protection



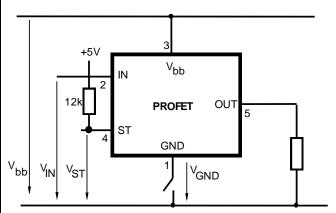
 V_{Z1} = 6.2 V typ., V_{Z2} = 70 V typ., R_{GND} = 150 Ω, R_{ST} = 15 kΩ, R_{I} = 20 kΩ typ.

Open-load detection

OFF-state diagnostic condition: $V_{OUT} > 3 \text{ V typ.}$; IN low

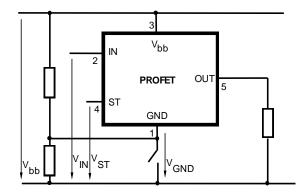


GND disconnect



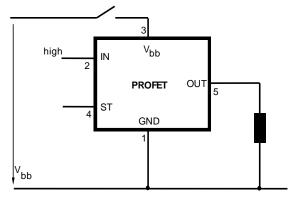
For V_{bb}=24V and V_{IN}=0V: V_{ST}>2.8V @ I_{ST} ≥ 0 if pulled up as shown. Any kind of load. In case of Input=high is $V_{OUT} \approx V_{IN} - V_{IN(T+)}$.

GND disconnect with GND pull up



Any kind of load. If $V_{GND} > V_{IN} - V_{IN(T+)}$ device stays off Due to $V_{GND} > 0$, no $V_{ST} = low$ signal available.

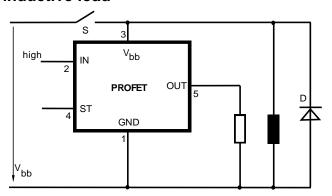
V_{bb} disconnect with energized inductive load



Normal load current can be handled by the PROFET itself.

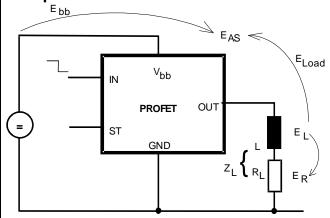


V_{bb} disconnect with charged external inductive load



If other external inductive loads L are connected to the PROFET, additional elements like D are necessary.

Inductive Load switch-off energy dissipation



Energy stored in load inductance:

$$E_{\rm L} = \frac{1}{2} \cdot {\rm L} \cdot {\rm I}_{\rm L}^2$$

While demagnetizing load inductance, the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = \int V_{ON(CL)} \cdot i_L(t) dt$$

with an approximate solution for $R_L > 0\Omega$:

$$E_{\text{AS}} = \frac{I_{\text{L}} \cdot L}{2 \cdot R_{\text{L}}} \cdot \left(V_{\text{bb}} + |V_{\text{OUT(CL)}}| \right) \cdot \ln \left(1 + \frac{I_{\text{L}} \cdot R_{\text{L}}}{|V_{\text{OUT(CL)}}|} \right)$$



Options Overview

all versions: High-side switch, Input protection, ESD protection and reverse battery protection with 150 Ω in GND connection, protection against loss of ground

Type BTS	410D2		410G2	ı	307	308
Logic version	D	E	G	H	307	300
Overtemperature protection with hysteresis			9	- 11		
$T_i > 150 ^{\circ}\text{C}$, latch function ¹⁰) ¹¹)	X			V		
, <i>•</i>	^		V	Х	v	X
Tj >150 °C, with auto-restart on cooling		Х	Х		Х	
Short circuit to GND protection						
switches off when $V_{\rm ON}>3.5$ V typ. and $V_{\rm bb}>8$ V typ ¹⁰⁾ (when first turned on after approx. 150 μ s)				Х		Х
switches off when <i>V</i> _{ON} >8.5 V typ. ¹⁰⁾ (when first turned on after approx. 150 μs)	Х	Х				
Achieved through overtemperature protection			Χ		X	
Open load detection						
in OFF-state with sensing current 6 μA typ. in ON-state with sensing voltage drop across power transistor	Х	Х	Х	Х	Х	Х
Undervoltage shutdown with auto restart	Х	Х	Х	Х	Х	Х
Overvoltage shutdown with auto restart	Х	Х	Х	Х	-	Х
Status feedback for						
overtemperature	Х	Х	Χ	Χ	Χ	Х
short circuit to GND	X	Х	-	Х	X	Х
short to V _{bb}	_12)	- ¹²)	_12)	Х	X	Х
open load	Х	Х	Χ	Х	X	Х
undervoltage	X	-	-	-	X	-
overvoltage	X	-	-	-	-	-
Status output type						
CMOS	Х					
Open drain		Х	Χ	Х	X	Х
Output negative voltage transient limit (fast inductive load switch off)						
to V _{bb} - V _{ON(CL)}	Х	Х	Х	Х	Х	Х
Load current limit						
high level (can handle loads with high inrush currents)	Х	Х				
low level (better protection of application)			Χ	Х	X	Х
Protection against loss of GND	Х	Х	Х	Х	Х	Х

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Latch except when V_{bb} - V_{OUT} < $V_{ON(SC)}$ after shutdown. In most cases V_{OUT} = 0 V after shutdown ($V_{OUT} \neq 0$ V only if forced externally). So the device remains latched unless V_{bb} < $V_{ON(SC)}$ (see page 4). No latch between turn on and $t_{d(SC)}$.

With latch function. Reseted by a) Input low, b) Undervoltage, c) Overvoltage

Low resistance short $V_{\rm bb}$ to output may be detected in ON-state by the no-load-detection



Timing diagrams

Figure 1a: V_{bb} turn on, :

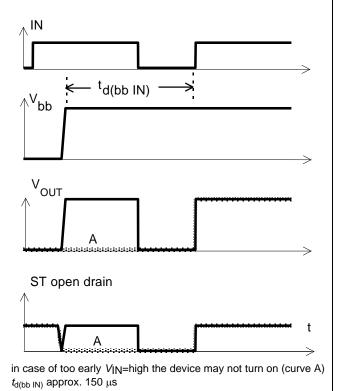


Figure 2a: Switching an inductive load,

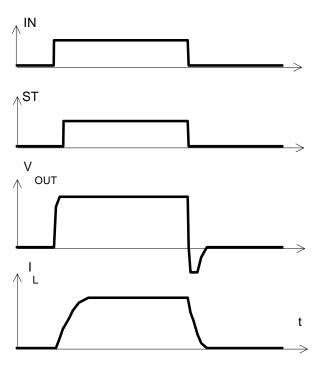
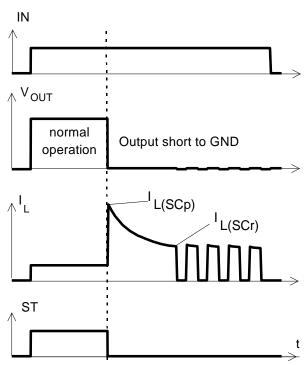


Figure 3a: Short circuit:

shut down by overtempertature, reset by cooling



Heating up requires several milliseconds, depending on external conditions. External shutdown in response to status fault signal recommended.

Figure 4a: Overtemperature:

Reset if $T_i < T_{it}$

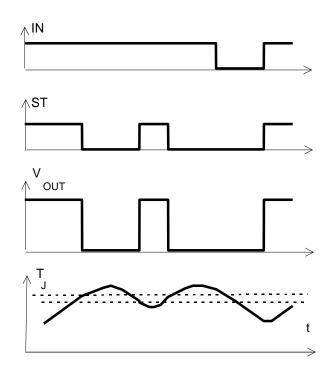
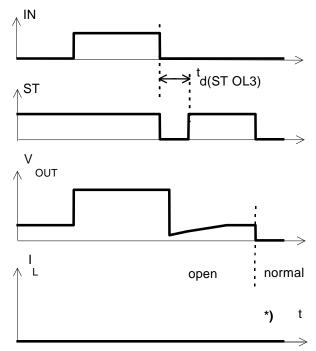




Figure 5a: Open load, : detection in OFF-state, turn on/off to open load



 $t_{\text{d}(\text{ST},\text{OL3})}$ depends on external circuitry because of high impedance

Figure 5b: Open load, : detection in OFF-state, open load occurs in off-state

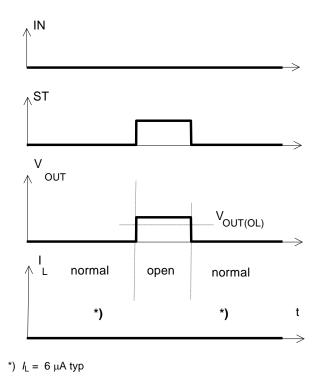


Figure 6a: Undervoltage:

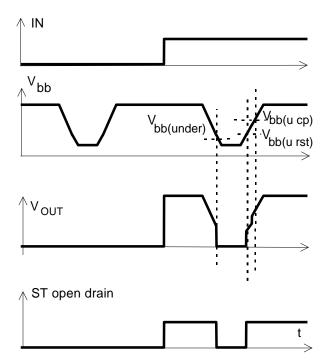
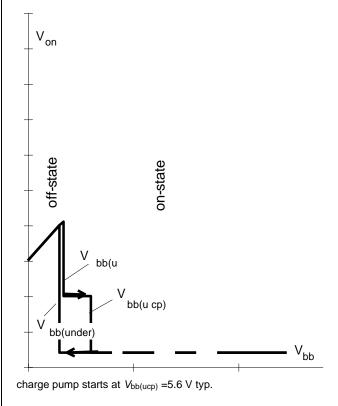


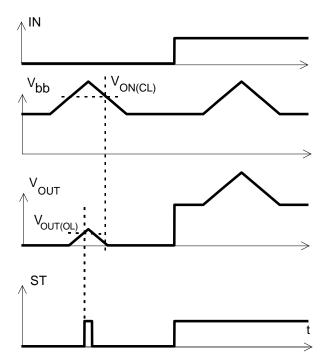
Figure 6b: Undervoltage restart of charge pump



^{*)} $I_L = 6 \mu A \text{ typ}$



Figure 7a: Overvoltage, no shutdown:

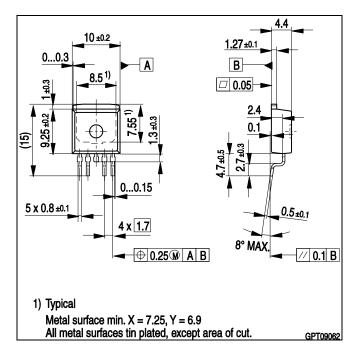




Package and Ordering Code

All dimensions in mm

PG-TO263-5-2	Ordering code
BTS307 E3062A	SP001104812



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